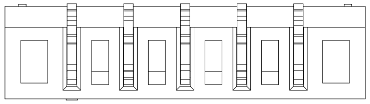
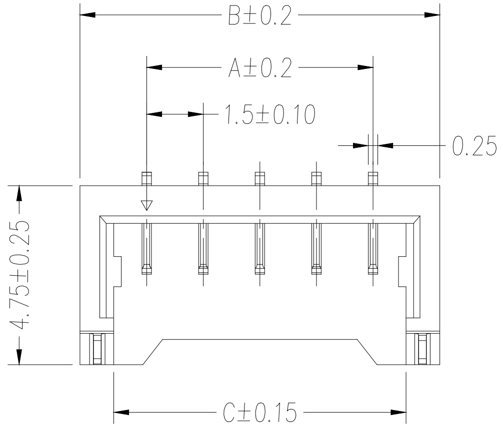
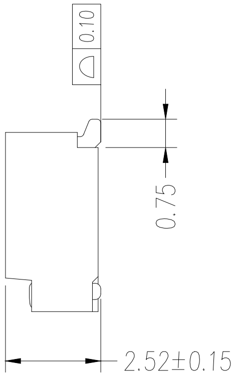
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD







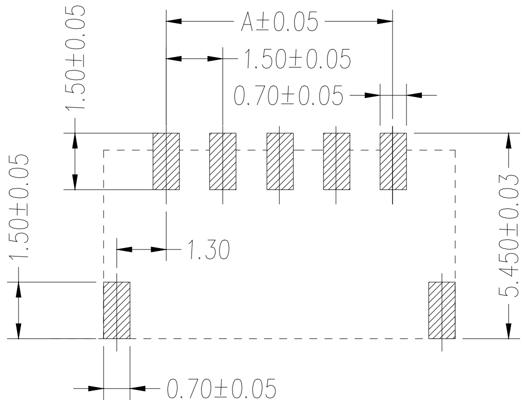
SPECIFICATIONS

Electrical
- Current Rating: 1A AC/DC
- Voltage Rating: 100V AC/DC
- Contact Resistance: ≤40mΩ
- Insulation Resistance: 500 MΩ MIN
- Withstanding Voltage: 500V AC/minute
- Temperature Range−Operating: −40℃～+105℃

Material
- Housing: LCP (UL94V−0),Black
- Terminal: Copper Alloy,Tin−Plated
- Solder Tab: Copper Alloy,Tin−Plated

Mates With Housing: FHG15006 Series

Circuits (n)	Part NO.	Dimensions		
		A	B	C
2	FWF15012−S02B23BKM	1.50	5.04	3.25
3	FWF15012−S03B23BKM	3.00	6.54	4.75
5	FWF15012−S05B23BKM	6.00	9.54	7.75



Ordering Information

FWF	150	12	—	S	XX	B	2	3	BK	M
1	2	3		4	5	6	7	8	9	10

1 Category: FWF−Wafer

2 Series Number: 150−Pitch1.50mm

3 Distinction No.: 12

4 Row Option: S−Single row

5 Circuits: XX

6 Entry Angle: B−90° Angle

7 Plating: 2−Matte tin Plated

8 Material−Resin: 3−LCP

9 Color−Resin: BK−Black

10 Packaging: M−Reel

THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY LEO	DATE 18/DEC/21	PART NO. FWF15012−SXXB23BKM
	X. ±0.30	X.° ±5°	CHECKED BY GISELLE	DATE 18/DEC/21	ITEM NO. FWF15012
DESIGN UNITS mm	X.X ±0.20	X.X° ±2°			TITLE Wire to Board Pitch 1.50mm(Wafer)
SCALE 5:1 / SIZE A4	X.XX ±0.15	X.XX° ±1°	DRAWN BY PYD	DATE 18/DEC/21	REV 0 / SHEET NO. 1/2
	X.XXX ±0.10	X.XXX° ±0.5°			

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Building Technology Cornerstone

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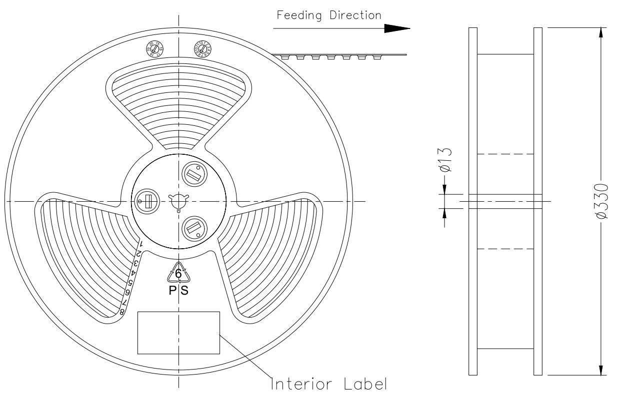
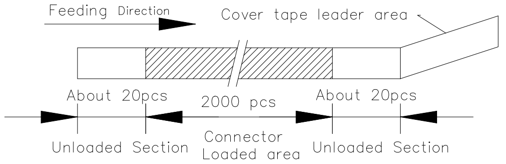
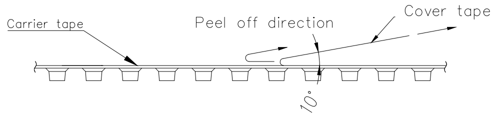
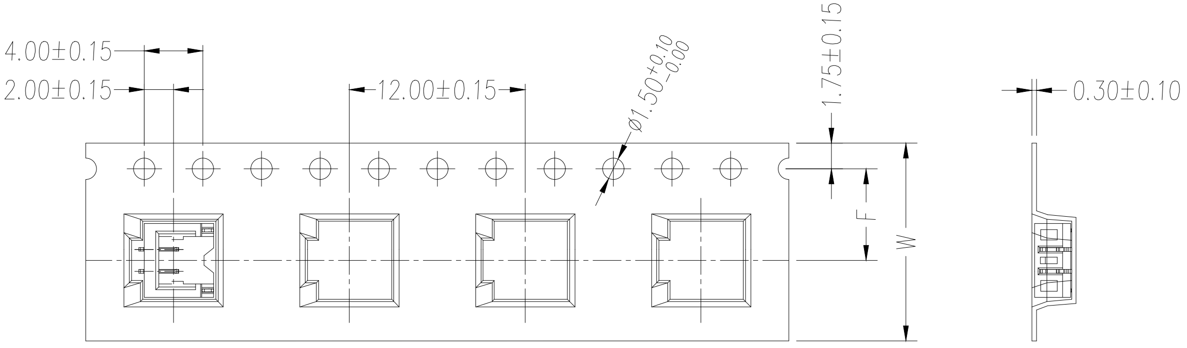
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



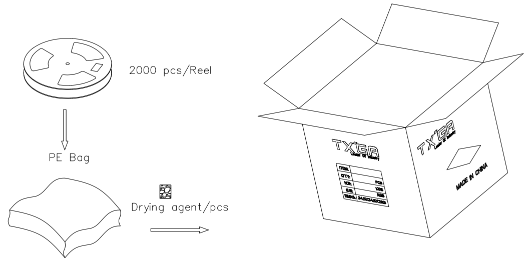
1. 10 sprocket hole cumulative tolerance±0.2
2. Carrier camber is within 1.0mm in 250mm
3. Material: Clear conductive polystyrene Alloy 100% recyclable
4. All dimensions meet EIA–481–3 requirements
5. Peel off force of cover tape & carrier tape: 20g~130g (0.2N~1.3N)
6. Component load per 13" reel: 2000 pcs







Circuits (n)	Dimensions		
	W	S	F
2	16	–	7.5
3	16	–	7.5
5	24	–	11.5



THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY LEO	DATE 18/DEC/21
	X. ±0.30	X.° ±5°	CHECKED BY GISELLE	DATE 18/DEC/21
DESIGN UNITS mm	X.X ±0.20	X.X° ±2°		
SCALE 5:1 SIZE A4	X.XX ±0.15	X.XX° ±1°	DRAWN BY PYD	DATE 18/DEC/21
	X.XXX ±0.10	X.XXX° ±0.5°		

PART NO. FWF15012–SXXB23BKM

ITEM NO. FWF15012

TXGA

Building Technology Cornerstone

TITLE Wire to Board Pitch 1.50mm(Wafer)

REV 0

SHEET NO. 2/2